## Product / Package Information

| | |
|---|---|
| **Package** | LFCSP - Sawn |
| **Body Size (mm)** | 3 X 3 X 0.65 |
| **Lead Count** | 8 |
| **Terminal Finish** | NiPdAu |

## Environmental Information

| | |
|---|---|
| **RoHS Compliant** | Yes |
| **High Temperature Compliant** | Yes |
| **Halogen Free Compliant** | Yes |
| **REACH SVHC Compliant** | Yes |

## Materials Declaration

### Molding Compound

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Silica(Amorphous) A | 60676-86-0 | 6.23E-03 | 75.00 | 750000 | 30.85 | 308503 |
| Other inorganic materials | Silica(Amorphous) B | 7631-86-9 | 1.16E-03 | 14.00 | 140000 | 5.76 | 57587 |
| Thermosets | Epoxy Resin | Proprietary | 6.23E-04 | 7.50 | 75000 | 3.09 | 30850 |
| Thermosets | Phenol Resin | Proprietary | 2.49E-04 | 3.00 | 30000 | 1.23 | 12340 |
| Other inorganic materials | Carbon Black | 1333-86-4 | 4.15E-05 | 0.50 | 5000 | 0.21 | 2057 |
| Subtotal | | | 8.30 E-03 | 100.00 | 1000000 | 41.13 | 411337 |

### Leadframe

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 9.72 E-03 | 97.5 | 975000 | 48.13 | 481265 |
| Copper & its alloys | Iron | 7439-89-6 | 2.34 E-04 | 2.35 | 23500 | 1.16 | 11600 |
| Copper & its alloys | Zinc | 7440-66-6 | 1.20 E-05 | 0.12 | 1200 | 0.06 | 592 |
| Copper & its alloys | Phosphorus | 7723-14-0 | 2.99 E-06 | 0.03 | 300 | 0.01 | 148 |
| Subtotal | | | 9.97 E-03 | 100.00 | 1000000 | 49.36 | 493605 |

### External Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Nickel & its alloys | Nickel | 7440-02-0 | 3.89 E-04 | 81.9 | 819149 | 1.93 | 19254 |
| Precious metals | Palladium | 7440-05-3 | 6.06 E-05 | 12.8 | 127660 | 0.30 | 3001 |
| Precious metals | Gold | 7440-57-5 | 2.52 E-05 | 5.3 | 53191 | 0.13 | 1250 |
| | | | 4.75 E-04 | 100.0 | 1000000 | 2.35 | 23505 |

### Bond Wires

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Gold | 7440-57-5 | 4.75 E-05 | 100.0 | 1000000 | 0.24 | 2350 |
| Subtotal | | | | | | | |

### Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 1.42 E-03 | 100.0 | 1000000 | 7.05 | 70515 |

### Die Attach

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Silver | 7440-22-4 | 4.57 E-05 | 77.00 | 770000 | 0.23 | 2262 |
| Other organic materials | Acrylic resin | Proprietary | 4.15 E-06 | 7.00 | 70000 | 0.02 | 206 |
| Other organic materials | Acrylate | Proprietary | 3.26 E-06 | 5.50 | 55000 | 0.02 | 162 |
| Other organic materials | Polybutadiene derivative | Proprietary | 2.67 E-06 | 4.50 | 45000 | 0.01 | 132 |
| Other organic materials | Epoxy resin | Proprietary | 1.48 E-06 | 2.50 | 25000 | 0.01 | 73 |
| Other organic materials | Butadiene Copolymer | Proprietary | 8.90 E-07 | 1.50 | 15000 | 0.00 | 44 |
| Others | Additive | Proprietary | 8.90 E-07 | 1.50 | 15000 | 0.00 | 44 |
| Others | Peroxide | Proprietary | 2.97 E-07 | 0.50 | 5000 | 0.00 | 15 |
| Subtotal | | | 5.93 E-05 | 100.0 | 1000000 | 0.29 | 2938 |

| | Weight (g) | Percentage (%) | PPM |
|---|---|---|---|
| **Package Totals** | **2.02 E-02** | **100** | **1000000** |

Control ID:MS011091/ 4134
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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